

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

SAMSUNG ELECTRONICS CO., LTD., AND
SAMSUNG ELECTRONICS AMERICA, INC.
Petitioner

v.

SINOTECHNIX LLC
Patent Owner

Case No. IPR2025-00332
U.S. Patent No. 7,951,626

**JOINT MOTION TO TERMINATE THE PROCEEDING;
AND
JOINT REQUEST TO TREAT THE SETTLEMENT AND LICENSE
AGREEMENT AS BUSINESS CONFIDENTIAL INFORMATION**

PETITIONER’S UPDATED EXHIBIT LIST

Petitioner Exhibit No.	DESCRIPTION
1001	U.S. Patent No. 7,951,626 (“’626 Patent”)
1002	Declaration of Dr. Ioannis Kymissis
1003	PCT Application Publication No. WO2002/059983 (“Eliashevich”)
1004	U.S. Patent No. 5,378,309 (“Rabinzohn”)
1005	U.S. Patent Application Publication No. 2003/0189212 (“Yoo”)
1006	U.S. Patent No. 6,444,410 (“Huang”)
1007	U.S. Patent Application Publication No. 2005/0281303 (“Horio”)
1008	U.S. Patent Application Publication No. 2006/0169993 (“Fan”)
1009	U.S. Patent No. 7,053,419 (“Camras”)
1010	U.S. Patent No. 6,229,160 (“Krames”)
1011	H. Xiao, “Introduction to Semiconductor Manufacturing Technology,” “Chapter 6,” Prentice Hall, 2001
1012	File History of U.S. Patent No. 7,951,626
1013	File History of U.S. Application No. 11/993,965
1014	L.F. Thompson, “Introduction to Microlithography,” “Chapter 1. Introduction to Photolithography,” <i>ACS Symposium Series</i> Vol. 219, 1983 (“Thompson”)
1015	D. J. Kim, “Characterization and Modeling of Positive Photoresist,” Memorandum No. UCB/ERL M84/65, 1984 (“Kim”)
1016	S. L. Morton et al., “Ultrasonic Sensor for Photoresist Process Monitoring,” <i>IEEE Transactions on Semiconductor Manufacturing</i> , Vol. 12, No. 3, August 1999 (“Morton”)
1017	E. J. Jewell et al., “The New Oxford American Dictionary,” Oxford University Press, p. 1286, 2001
1018	Docket Control Order in <i>Sinotechnix LLC v. Samsung Electronics et al.</i> , 2:24-cv-544-JRG-RSP
1019	Judicial Caseload For Eastern District of Texas
1020	Judge Gilstrap’s Case Schedule (May 4, 2026)
1021	T. Nakazawa et al., “Compact and monolithic coarse wavelength-division multiplexer-demultiplexer fabricated by use of a high-spatial-frequency transmission grating buried in a slab waveguide,” Vol. 29, Issue 11, pp. 1188-1190, 2004 (“Nakazawa”)
1022	U.S. Patent Application No. 2006/0231852 (“Kususe”)
1023	H. Jansen et al., “A survey on the reactive ion etching of silicon in

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	microtechnology,” Micromechanics Europe 1995 Technical Digest, 1995 (“Jansen”)
1024	<i>Sotera</i> Stipulation
1025	Updated <i>Sotera</i> Stipulation
1026	Samsung Electronics Co., Ltd. & Sinotechnix LLC’s Settlement and License Agreement (the “Agreement”) (CONFIDENTIAL)

Pursuant to 35 U.S.C. § 317(a) and 37 C.F.R. §§ 42.72 and 42.74, and the Board’s authorization on August 5, 2025 (EX3001), Petitioner Samsung Electronics Co., Ltd. and Samsung Electronics America, Inc. (“Samsung”) and Patent Owner Sinotechnix LLC (“Sinotechnix”) (collectively, “the Parties”) jointly move to terminate the present *inter partes* proceeding in light of the settlement of their dispute regarding U.S. Patent No. 7,951,626 (the “’626 Patent”), and jointly request to treat as business confidential information the copy of the settlement agreement filed along with this paper (Confidential Exhibit 1026).

I. Introduction

The Petition in this proceeding was filed on February 13, 2025, by Samsung. On June 11, 2025, Patent Owner filed its request for discretionary denial. Paper 8. Petitioner’s opposition to discretionary denial and the Patent Owner’s Preliminary Response (“POPR”) were originally due on July 11, 2025. In anticipation of the settlement of their dispute, the Parties requested and the Board subsequently granted an extension of time on July 7, 2025, so that the Petitioner’s opposition to discretionary denial and the POPR are now due on August 11, 2025. EX3102. The Board has not yet issued a decision on institution.

On July 31, 2025, the Parties entered into a Settlement and License Agreement (the “Agreement”) that resolves the dispute regarding the ’626 Patent. *See* Confidential Exhibit 1026. The Parties contacted the Board by email to request

authorization to file a joint motion to terminate this IPR proceeding and a joint request to file the Agreement as business confidential information. The Board granted the authorization in a responsive email on August 5, 2025. EX3001.

II. Joint Motion To Terminate The Proceeding

The Parties jointly request that this *inter partes* review be terminated in light of the settlement of their dispute regarding the '626 Patent.

Under 35 U.S.C. § 317(a), “[a]n *inter partes* review instituted under this chapter shall be terminated with respect to any petitioner upon the joint request of the petitioner and the patent owner, unless the Office has decided the merits of the proceeding before the request for termination is filed.” Additionally, the Board has explained:

There are strong public policy reasons to favor settlement between the parties to a proceeding. . . . The Board expects that a proceeding will terminate after the filing of a settlement agreement, unless the Board has already decided the merits of the proceeding. 35 U.S.C. §§ 317(a), 327.

Consolidated Trial Practice Guide (November 2019) (“TPG”), page 86 § II.N.

Termination of the present *inter partes* review is appropriate because the Parties have settled their dispute regarding the '626 Patent and the Office has not yet decided the merits of this proceeding.

Additionally, a true and complete copy of the Agreement is being filed along with this paper. *See* Confidential Exhibit 1026. The Parties certify that there are no other agreements or understandings between the Parties, including any collateral agreements, made in connection with, or in contemplation of, the termination of this proceeding.

Therefore, the Parties respectfully submit that this *inter partes* review should be terminated.

III. Joint Request To Treat Settlement Agreement As Business Confidential Information

The Parties jointly request that the Agreement filed as Confidential Exhibit 1026 be treated as business confidential information and be kept separate from the publicly available files of the '626 Patent.

Section 317(b) provides that:

At the request of a party to the proceeding, the agreement or understanding shall be treated as business confidential information, shall be kept separate from the file of the involved patents, and shall be made available only to Federal Government agencies on written request, or to any person on a showing of good cause.

Likewise, 37 C.F.R. § 42.74(c) provides that:

A party to a settlement may request that the settlement be treated as business confidential information and be kept separate from the files of an involved patent or application. The request must be filed with the settlement. If a timely request is filed, the settlement shall only be available:

- (1) To a Government agency on written request to the Board; or
- (2) To any other person upon written request to the Board to make the settlement agreement available, upon with the fee specified in § 42.15(d) and on a showing of good cause.

The present request, which is being filed along with the Agreement, is timely and in accordance with the foregoing authority.

Therefore, the Parties respectfully submit that this request for confidential treatment should be granted.

Dated: August 7, 2025

Respectfully submitted,

/Taeg Sang Cho/

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CERTIFICATE OF SERVICE

The undersigned certifies that on August 7, 2025, complete a copy of the foregoing was served on counsel of record for the Patent Owner by filing the documents through P-TACTS and by sending via electronic mail to the following addresses:

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